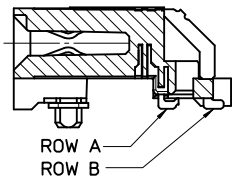
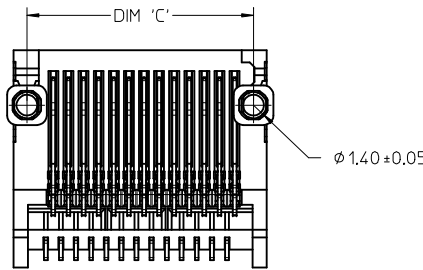
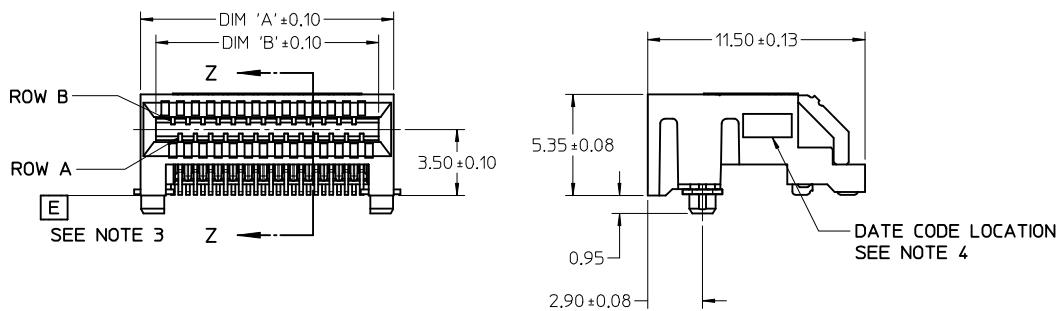
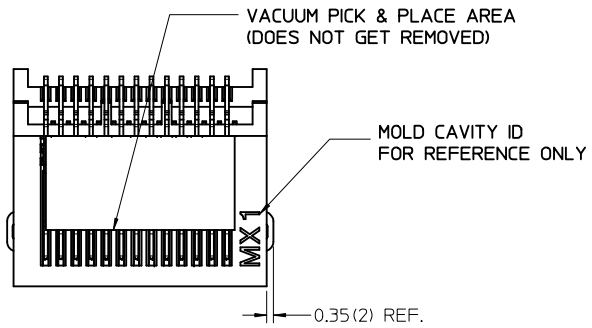
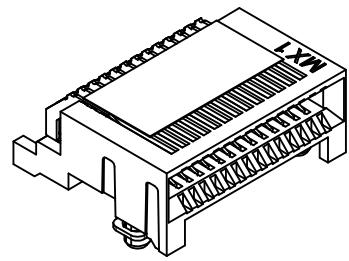


CIRCUIT SIZE	ITEM NUMBER	PLATING OPTION	DIM 'A'	DIM 'B'	DIM 'C'
26	75586-0101	OPTION 1	13.40	11.80	12.00
26	75586-0102	OPTION 2	13.40	11.80	12.00
38	75586-0103	OPTION 1	18.20	16.60	16.80
38	75586-0104	OPTION 2	18.20	16.60	16.80
68	75586-0105	OPTION 1	30.20	28.60	28.80
68	75586-0106	OPTION 2	30.20	28.60	28.80



- NOTES
- MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED,
UL 94V-0, BLACK
TERMINALS - COPPER ALLOY
 - PLATING:
OPTION 1
CONTACT AREA - 0.38 µm MIN GOLD OVER 2.54 µm MIN NICKEL
SOLDER FOOT AREA - 2.54 - 5.09 µm TIN OVER 1.27 µm MIN NICKEL.
OPTION 2
CONTACT AREA - 0.76 µm MIN GOLD OVER 2.54 µm NICKEL
SOLDER AREA - 2.54 - 5.09 µm TIN OVER 1.27 µm MIN NICKEL
 - TERMINAL SOLDER FEET TO BE COPLANAR WITHIN 0.10/004 MEASURED FROM FRONT HOUSING STAND OFF (DATUM E)
 - DATE CODE: 4 DIGIT (3 DIGIT DATE, 1 DIGIT YEAR)
 - CIRCUIT IDENTIFIER: SEE APPROPRIATE INDUSTRY SPECIFICATION FOR LOCATION OF PIN 1
 - TO BE USED WITH EXTERNAL CABLES (74546 & 74547 SERIES) AND GUIDE FRAMES (74540 & 74548 SERIES)
 - TESTER/ANALYZER CABLES AVAILABLE (74557 & 74558 SERIES)
 - PACKAGED PER PACKAGING SPECIFICATION: PK-75586-002
 - CONFORMS TO PRODUCT SPECIFICATION: PS-75586-001
 - THIS PART CONFORMS TO CLASS C REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.



REV NOTE 2

EC NO: UCP2015-0453

DRWN:KB INGHAM 2014/07/31

CHKD: TMCLELLAND 2014/08/01

APPR: TMCLELLAND 2014/08/01

REV

C2

QUALITY SYMBOLS

▽=0

▽=0

▽=0

DESCRIPTION

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.13	± ---
1 PLACE	± 0.25	± ---
0 PLACE	±	±

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE

MM ONLY

DRAWN BY	DATE
KLANG	12/06/2006
CHECKED BY	DATE
JSWENSON	12/06/2006
APPROVED BY	DATE
MBANAKIS	12/06/2006

MATERIAL NO.

SEE CHART

SIZE

C

SCALE

5:1

DESIGN UNITS

METRIC

THIRD ANGLE PROJECTION

TITLE

IPASS R/A CONNECTOR
EXTERNAL ASSEMBLY
SOLDER RING

molex

DOCUMENT NO.

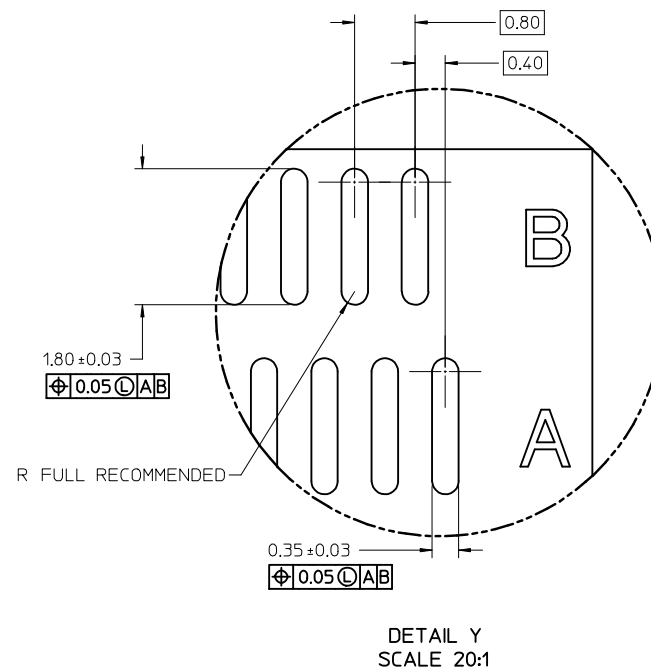
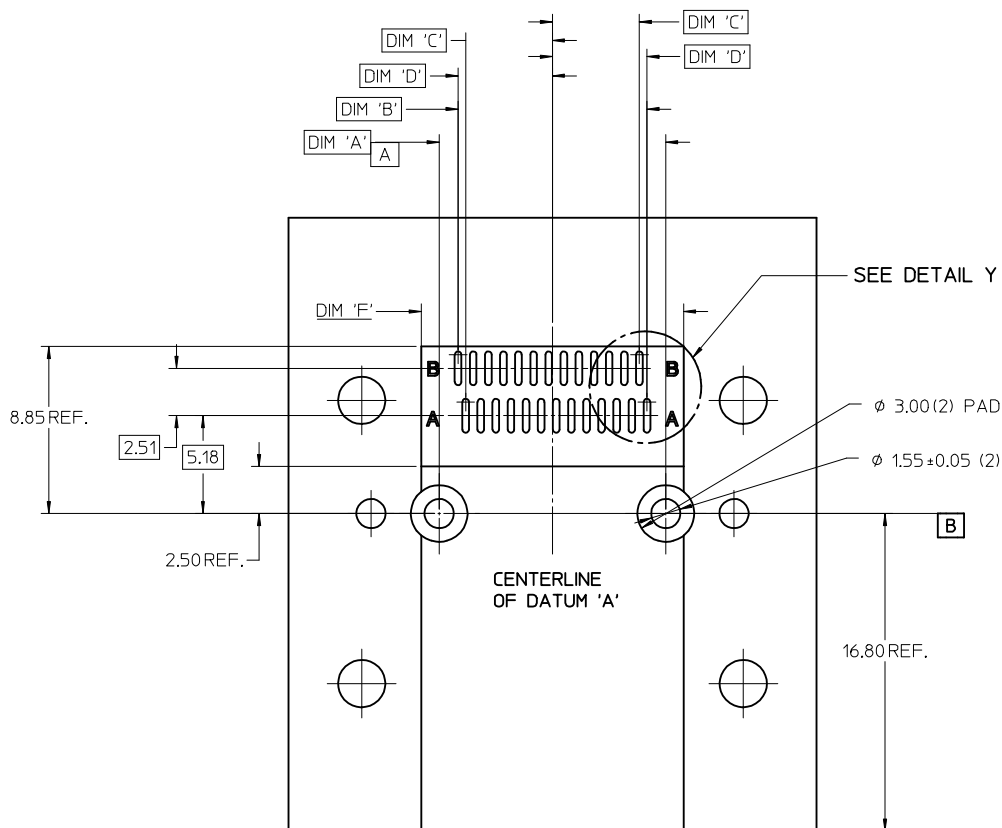
SD-75586-005

SHEET NO.

1 OF 6

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX
INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

MOTHERBOARD FOOTPRINT RECOMMENDATION

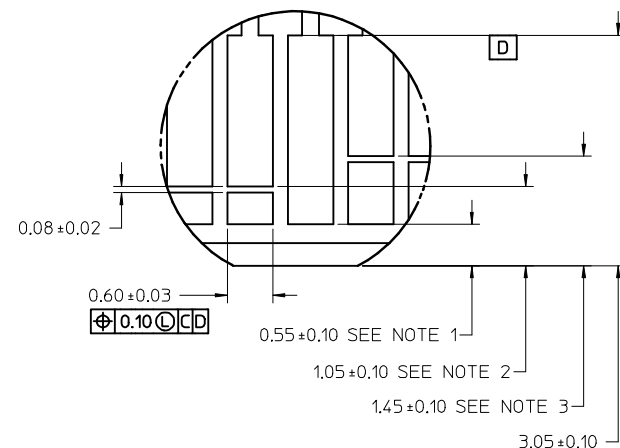
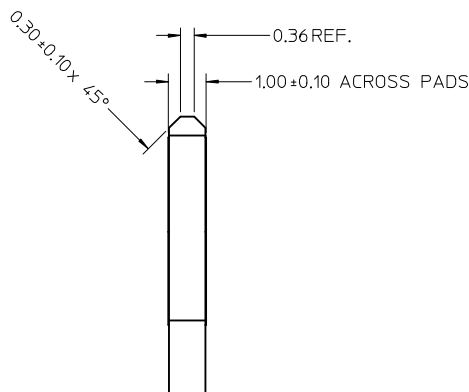
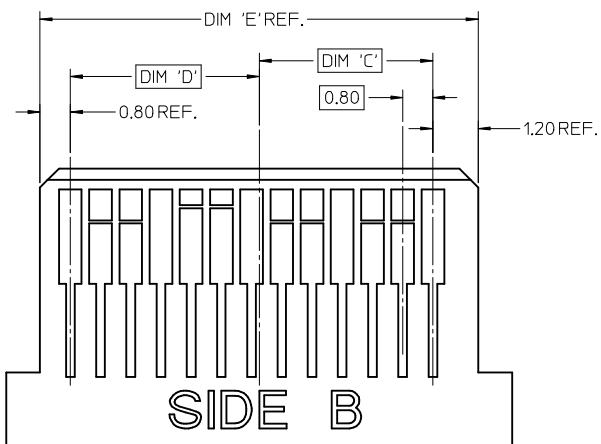
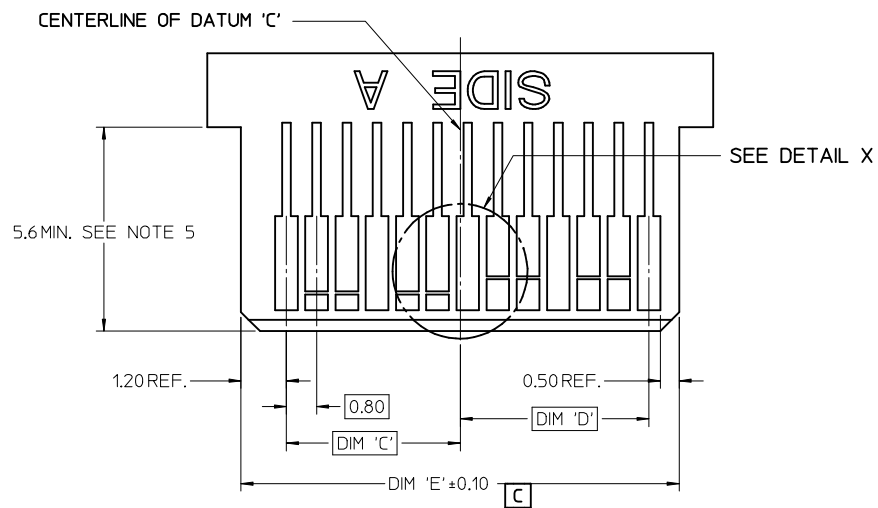


- NOTES:**
- SEE 74540 OR 74548 SERIES FOR GUIDE FRAME FOOT PRINT AND KEEP OUT AREA.

		PEG TO PEG	FIRST PAD TO LAST PAD	CENTERLINE TO PAD	CENTERLINE TO PAD	MODULE BOARD WIDTH	CONNECTOR WIDTH
CIRCUIT SIZE	TERM/SIDE 'N'	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'	DIM 'F'
26	13	12.00	10.00	4.60	5.00	11.60	13.90
38	19	16.80	14.80	7.00	7.40	16.40	18.70
68	34	28.80	26.80	13.00	13.40	28.40	30.70

SEE SHEET 1 EC NO: UCP2015-0453 DRAWN BY: DRWINKINGHAM 2014/07/31 CHKD: TMCLELLAND 2014/08/01 APPR: TMCLELL 2014/08/01 C2	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
					DRAWN BY KLANG	DATE 12/06/2006	TITLE IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING					
					CHECKED BY JSWENSON	DATE 12/06/2006	molex					
					APPROVED BY MBANAKIS	DATE 12/06/2006						
					MATERIAL NO.							DOCUMENT NO.
			ANGULAR ±1/2°		SEE CHART		SD-75586-005				2 OF 6	
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

MODULE BOARD FOOTPRINT RECOMMENDATION



DETAIL X
SCALE 20:1

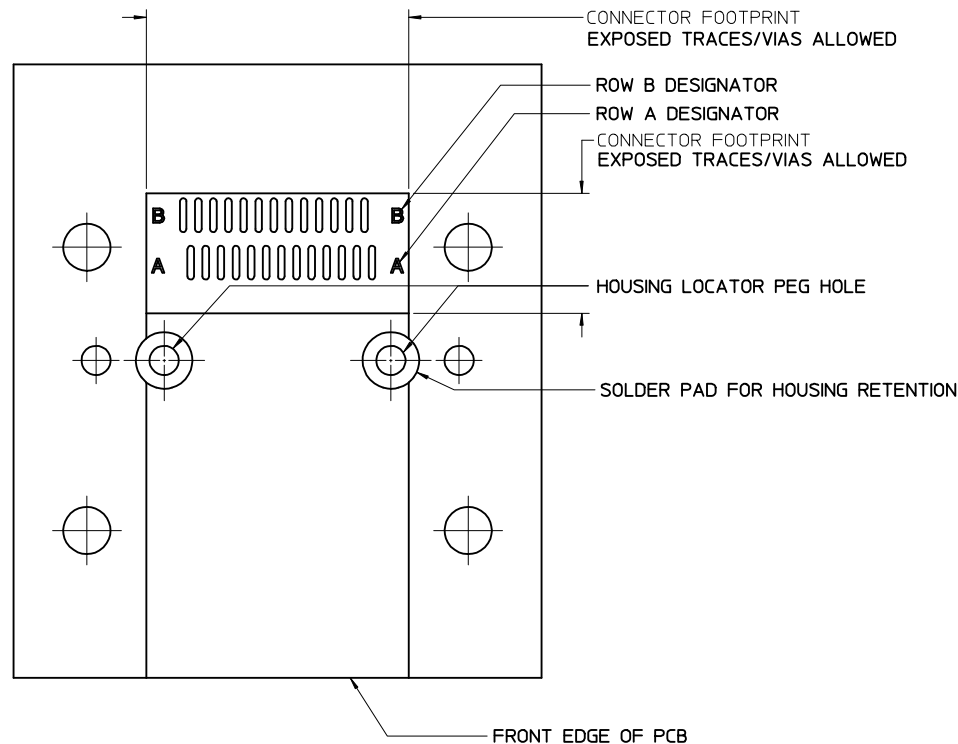
NOTES:

1. PAD CONFIGURATION FOR FIRST MATE.
2. PAD CONFIGURATION FOR SECOND MATE.
3. PAD CONFIGURATION FOR THIRD MATE (HIGH SPEED SIGNALS).
4. FOR PIN ASSIGNMENTS AND MATING SEQUENCE (1ST, 2ND, 3RD), SEE APPLICABLE SPECIFICATION.
5. MINIMUM STEP REQUIRED IF PCB MADE WIDER THAN CARD TONGUE.

CIRCUIT SIZE	TERM/SIDE 'N'	CENTERLINE TO PAD			MODULE BOARD WIDTH
		DIM 'C'	DIM 'D'	DIM 'E'	
26	13	4.60	5.00	11.60	
38	19	7.00	7.40	16.40	
68	34	13.00	13.40	28.40	

SEE SHEET 1 EC NO: UCP2015-0453 DRAWN BY: DRWNBINGHAM 2014/07/31 CHKD: TMCLELLAND 2014/08/01 APPR: TMCLELL 2014/08/01 C2	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
				mm	INCH	DRAWN BY KLANG	DATE 12/06/2006	TITLE IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING molex		
			4 PLACES	± ---	± ---	CHECKED BY JSWENSON	DATE 12/06/2006			
			3 PLACES	± ---	± ---	APPROVED BY	DATE			
			2 PLACES	± 0.13	± ---	MBANAKIS	12/06/2006			
			1 PLACE	± 0.25	± ---	MATERIAL NO.		DOCUMENT NO.		
			0 PLACE	±	±	SEE CHART		SD-75586-005		
			ANGULAR ±1/2°					SHEET NO.		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				3 OF 6

CONNECTOR FOOTPRINT ZONE IDENTIFICATION



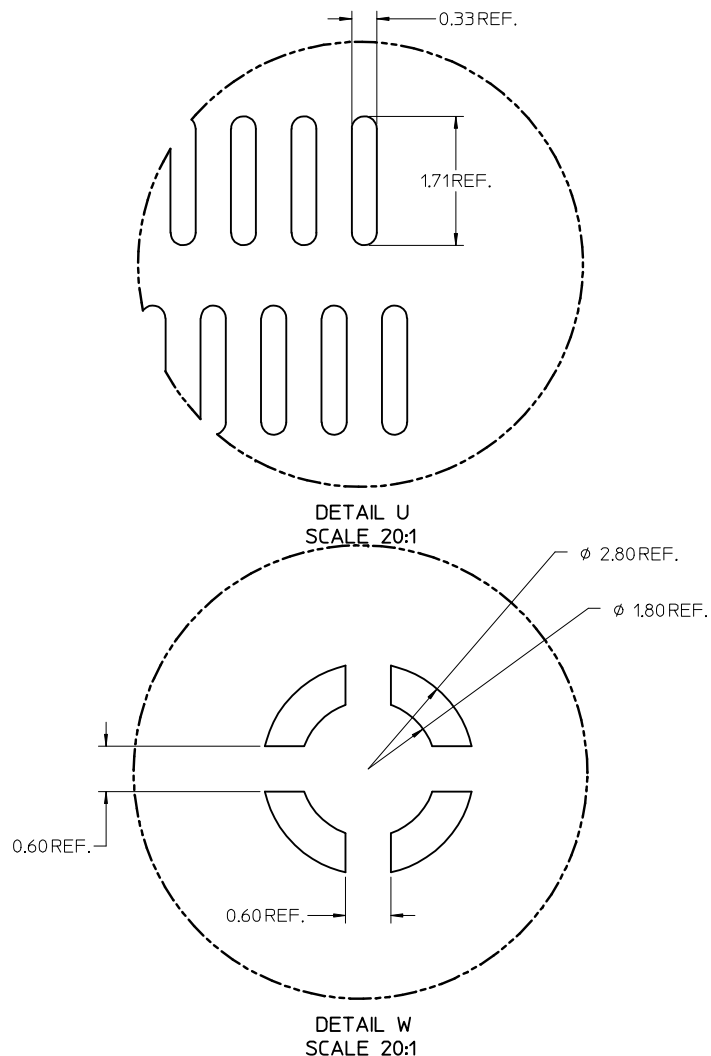
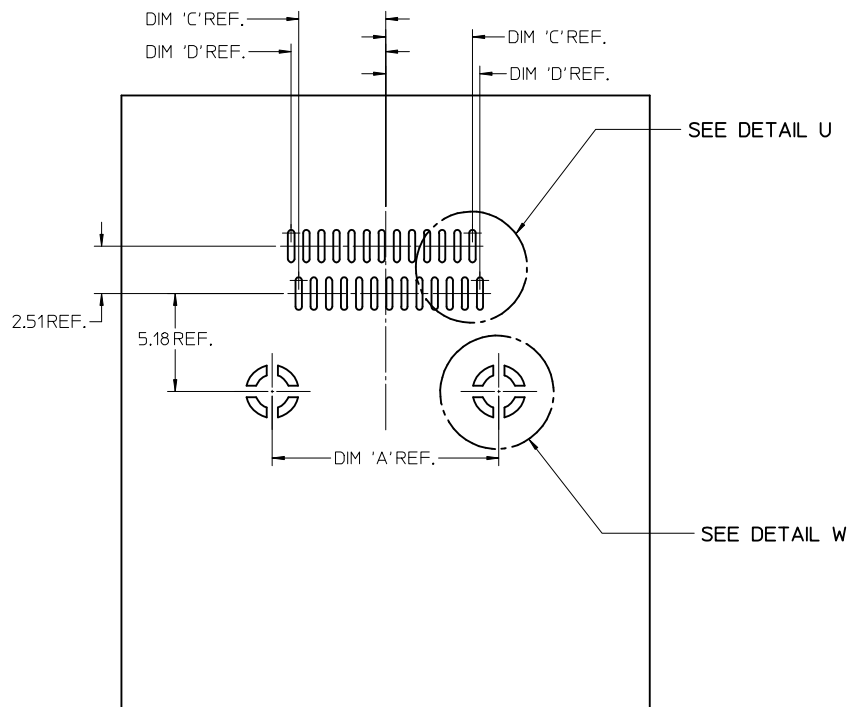
SEE SHEET 1 EC NO: UCP2015-0453 DRAWN BY: DRWNBINGHAM 2014/07/31 CHKD: TMCLELLAND 2014/08/01 APPR: TMCLELL 2014/08/01 C2	REV	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	 THIRD ANGLE PROJECTION	TITLE IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING molex						
						MM ONLY		5:1	METRIC								
						F=0	mm	INCH	DRAWN BY			DATE	MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
									KLANG			12/06/2006				SD-75586-005	4 OF 6
									CHECKED BY			DATE					
									JSWENSON			12/06/2006					
									APPROVED BY			DATE					
						MBANAKIS	12/06/2006										
						ANGULAR ±1/2°		SEE CHART									
						DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE C				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

NOTES:

- 1. STENCIL RECOMMENDATION IS A GUIDELINE ONLY.
- 2. MANUFACTURING PROCESS PARAMETERS WILL DEFINE THE ACTUAL STENCIL DEFINITION.
- 3. RECOMMENDED STENCIL THICKNESS IS 0.13MM.

SOLDER STENCIL RECOMMENDATION

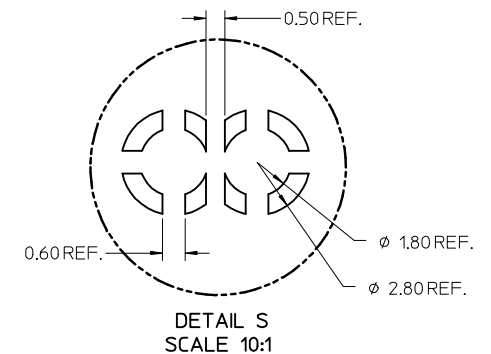
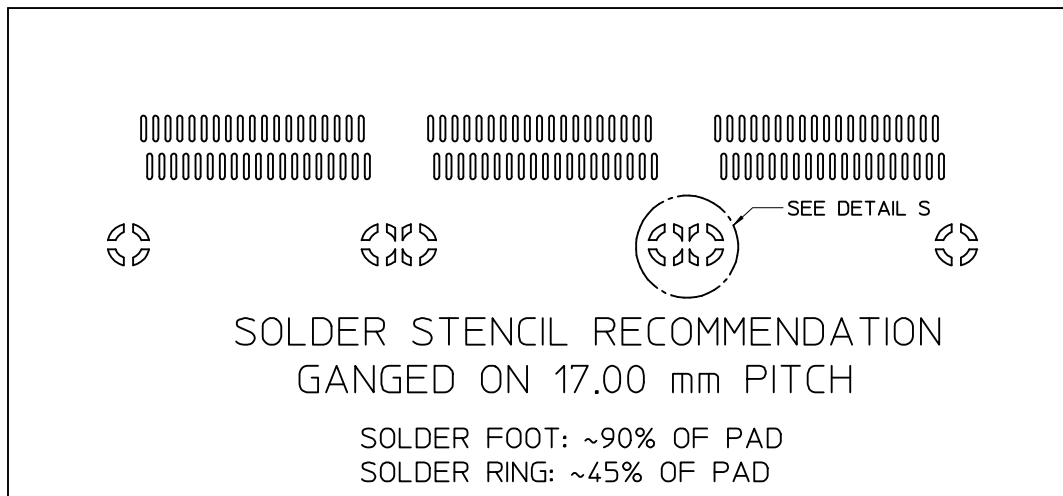
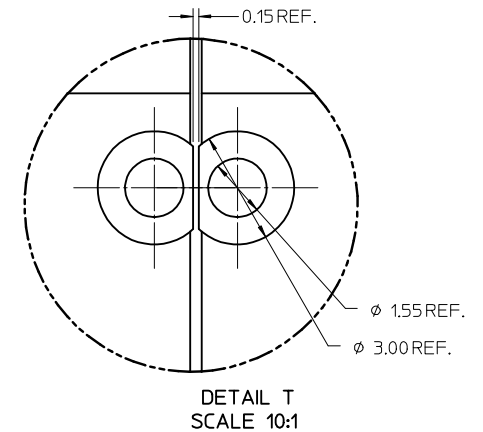
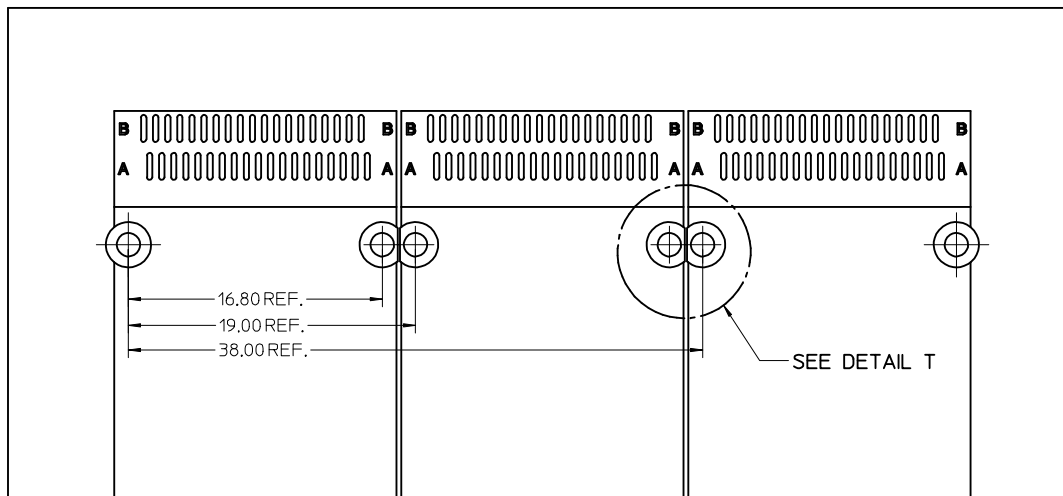
SOLDER FOOT: ~90% OF PAD
SOLDER RING: ~45% OF PAD



CIRCUIT SIZE	TERM/SIDE 'N'	DIMENSIONS		
		PEG TO PEG	CENTERLINE TO PAD	CENTERLINE TO PAD
		DIM 'A'	DIM 'C'	DIM 'D'
26	13	12.00	4.60	5.00
38	19	16.80	7.00	7.40
68	34	26.80	13.00	13.40

SEE SHEET 1 EC NO: UCP2015-0453 DRAWN BY: DRWNBINGHAM 2014/07/31 CHKD: TMCLELLAND 2014/08/01 APPR: TMCLELL 2014/08/01 C2	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
				mm	INCH	DRAWN BY KLANG	DATE 12/06/2006	TITLE IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING	
			4 PLACES ± ---	± ---	CHECKED BY JSWENSON	DATE 12/06/2006			
			3 PLACES ± ---	± ---	APPROVED BY MBANAKIS	DATE 12/06/2006			
			2 PLACES ± 0.13	± ---	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-75586-005			
			1 PLACE ± 0.25	± ---	SHEET NO. 5 OF 6				
			0 PLACE ±	± ---	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
			ANGULAR ± 1/2°						
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						
			REV	C2					

38 CIRCUIT GANGED ON 19.00 mm CENTERLINE



NOTES:

1. STENCIL RECOMMENDATION IS A GUIDELINE ONLY.
2. MANUFACTURING PROCESS PARAMETERS WILL DEFINE THE ACTUAL STENCIL DEFINITION.
3. RECOMMENDED STENCIL THICKNESS IS 0.13MM.

SEE SHEET 1 EC NO: UCP2015-0453 DRAWN BY: DRWNBINGHAM 2014/07/31 CHKD: TMCLELLAND 2014/08/01 APPR: TMCLELLAND 2014/08/01	REV	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
							DRAWN BY KLANG		DATE 12/06/2006	TITLE IPASS R/A CONNECTOR EXTERNAL ASSEMBLY SOLDER RING molex		
							CHECKED BY JSWENSON		DATE 12/06/2006			
							APPROVED BY MBANAKIS		DATE 12/06/2006			
							MATERIAL NO.		DOCUMENT NO.			SHEET NO. 6 OF 6
							SEE CHART		SD-75586-005			